

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1-14. (Canceled)

15. (Previously Presented) A micromachined structure, comprising:

a substrate;

a first wet-etched pit disposed in the substrate;

a second wet-etched pit disposed in the substrate, the second wet-etched pit
extending into the substrate a greater depth than the first wet-etched pit
and comprising a flat surface parallel to the upper surface of the substrate;
and

a dry-etched pit disposed between, and adjacent to, the first and second wet-
etched pits.

16. (Previously Presented) The micromachined structure of claim 15, wherein the substrate comprises <100> silicon.

17. (Previously Presented) The micromachined structure of claim 15, wherein the first wet-etched pit comprises a flat surface parallel to the upper surface of the substrate.

18. (Previously Presented) The micromachined structure of claim 17, comprising at least one of a VCSEL or a photodetector mounted to the flat surface of the second wet-etched pit.

19. (Previously Presented) A micromachined structure comprising:

a substrate;

a first wet-etched pit disposed in the substrate;

a second wet-etched pit disposed in the substrate, the second wet-etched pit
extending into the substrate a greater depth than the first wet-etched pit;
and
a dry-etched pit disposed between, and adjacent to, the first and second wet-
etched pits;
wherein the dry-etched pit is disposed within the second wet-etched pit and
wherein the dry-etched pit circumscribes the first wet-etched pit..

20. (Previously Presented) The micromachined structure of claim 15, wherein the first wet-etched pit comprises a V-shaped cross-section.

21. (Previously Presented) A micromachined structure comprising:

a substrate;
a first wet-etched pit disposed in the substrate;
a second wet-etched pit disposed in the substrate, the second wet-etched pit
extending into the substrate a greater depth than the first wet-etched pit;
and
a dry-etched pit disposed between, and adjacent to, the first and second wet-
etched pits;
wherein the first wet-etched pit comprises a V-shaped cross-section and the
second wet-etched pit comprises a pyramidal pit.

22. (Previously Presented) The micromachined substrate of claim 21, comprising a ball lens disposed in the second wet-etched pit and an optical fiber disposed in the first wet-etched pit.

23. (Previously Presented) The micromachined structure of claim 15, wherein the dry-etched pit is a linear trench.

24-30. (Canceled)